GOVERNMENT OF INDIA
MINISTRY OF ELECTRONICS AND INFORMATION TECHNOLOGY
LOK SABHA
UNSTARRED QUESTION NO. 2061
TO BE ANSWERED ON: 11.02.2026

SEMICONDUCTOR MANUFACTURING IN BIHAR

2061. SHRI RAJIV PRATAP RUDY:

Will the Minister of ELECTRONICS AND INFORMATION TECHNOLOGY be pleased to state:

(a) the details of semiconductor manufacturing units currently operational and those recently approved or proposed including those under the India Semiconductor Mission (ISM), State/UT-wise particularly in the State of Bihar;
(b) the present value and the major countries of semiconductor imports and exports with the country;
(c) the present and projected share of India in the global semiconductor market and the revenue generated thereof;
(d) the specific incentives and schemes in place to attract foreign investment and support domestic companies under the ISM including the details of the budget-sanctioned and investment done so far and the timeline of the mission; and
(e) the impact of the mission on reducing import dependence and creating jobs?

ANSWER

MINISTER OF STATE FOR ELECTRONICS AND INFORMATION TECHNOLOGY
(SHRI JITIN PRASADA)

(a) to (e): The semiconductor development strategy is inspired by Hon'ble Prime Minister's vision of Atmanirbhar Bharat and Make in India, Make for the world. As part of this strategy, India aims to develop a complete ecosystem, ranging from design, fabrication, assembly, testing, packaging and module manufacturing. India's Semiconductor strategy builds on the success of the electronics manufacturing. India is providing the most competitive incentives though following programmes to promote electronics/semiconductor manufacturing across the country, thereby increasing India's share in global electronics markets:

a) Semicon India Programme
b) PLI Scheme for IT Hardware and Large-Scale Electronics manufacturing
c) Electronics Component Manufacturing Scheme (ECMS)
d) Scheme for Promotion of Manufacturing of Electronic Components and Semiconductors (SPECS)
e) Electronics Manufacturing Clusters Scheme (EMC)
f) Modified Special Incentive Package Scheme (M-SIPS)

Given the foundational nature of semiconductor industry for the economy, the Government launched the 'Semicon India Programme' with a total outlay of Rs. 76,000 crore for the development of semiconductor and display manufacturing ecosystem in the country. Following are salient achievements under this Programme:

- Government has approved 10 projects with envisaged investments of about Rs. 1.6 Lakh Crore which includes 2 fabs and 8 packaging units. These units inter-alia include CMOS (Silicon) fab, Silicon Carbide fab, advanced packaging, memory packaging, etc. These projects are in various stages of implementation and pilot

production has started in 4 units. The details of the projects are provided at **Annexure**.

- 24 chip design projects have been supported through startups. 16 have completed tapeouts and 13 have received VC funding.
- 350 universities have been provided access to EDA tools, used by 65 thousand engineers

The Economic Survey 2025-26 notes that electronics exports reached $22.2 billion in the first half of FY26, which would soon propel the sector to be the 2nd highest export category by value. The momentum gained in the electronics/semiconductor industry has had a ripple effect on all allied sectors. The growth of electronics manufacturing can be seen from the following statistics:

#	**2014-15**	**2024-25**	**Remarks**
Production of electronics goods (Rs.)	~1.9 Lakh Cr	~11.3 Lakh Cr	Increased 6 times
Export of electronics goods (Rs.)	~38 thousand Cr	~3.27 Lakh Cr	Increased 8 times

Semiconductor Industry is a foundational Industry having implications across various sectors of the economy. The Semiconductor mission is expected to cater to the chip requirements of sectors such as consumer appliances, industrial electronics, automobiles, power electronics, telecommunications, aerospace etc thereby reducing import dependence. Semiconductor manufacturing is a highly specialised industry requiring complex manufacturing process. Therefore, most of the jobs created in this industry are skilled jobs. Further, these units are expected to have a cascading effect on employment generation in the other sectors and the supply chain down the line.

Union Budget for 2026-27 has also announced ISM 2.0 to further expand semiconductor manufacturing ecosystem.

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Annexure

Details of approved semiconductor manufacturing projects:

1. **Micron Technology Inc.** is establishing semiconductor manufacturing facility in Gujarat with an investment of Rs.22,516 crore. Micron's facility in India will enable assembly and test manufacturing for both DRAM and NAND products and address demand from domestic and international markets. The production capacity is around 14 million units per week.
2. **Tata Electronics Private Limited (TEPL)** is establishing semiconductor manufacturing facility in Gujarat with an investment of Rs. 91,526 crore. The fab facility will be set up in technology partnership with PSMC, Taiwan. The production capacity of the project would be around 50,000 wafer starts per month (WSPM).
3. **Tata Electronics Private Limited (TEPL)** is establishing semiconductor manufacturing facility in Assam with an investment of Rs.27,120 crores. The facility will use indigenous semiconductor packaging technologies with a production capacity of 48 million units per day.
4. **CG Power and Industrial Solutions Limited** is establishing semiconductor manufacturing facility in Gujarat with an investment of Rs. 7,584 crore. The facility will be set up as a joint venture partnership with Renesas Electronics America Inc., USA, and STARS Microelectronic, Thailand. The Technology would be provided for this facility by Renesas Electronics Corporation, Japan and STARS Microelectronic, Thailand. The production capacity would be around 15.07 million units per day.
5. **Kaynes Technology India Limited (KTIL)** is establishing semiconductor manufacturing facility in Gujarat with an investment of Rs. 3,307 crores for Wire bond Interconnect, Substrate Based Packages. The Technology would be provided by ISO Technology Sdn. Bhd. and AOI Electronics Co. Ltd. (AOI). The facility will have the capacity to produce more than 6.33 million chips per day.
6. HCL – Foxconn (VSIPL) is establishing semiconductor manufacturing facility in Uttar Pradesh with an investment of Rs 3,706 crores for display driver ICs (DDIC) using Gold (Au) Bump technology along with chip probing facilities and die processing services. The Technology would be provided by Hon Hai, Taiwan. The facility will be set up as a joint venture partnership between VSIPL and Foxconn, India. The production capacity would be around 20K wafers per month/36 million chips per month.
7. **3D Glass Solutions Inc. (3DGS)** is establishing semiconductor manufacturing facility in Odisha with an investment of Rs. 1,943 crores. The plant will handle the assembly of packaged products such as Flip Chip Ball Grid Array (FCBGA) assembly, Radio Frequency System in Package (RF SiP), Antenna in Package System in Package (AiP SiP), glass interposers with passives and silicon bridges and 3D Heterogeneous Integration (3DHI) modules. The Proposed installed capacity for glass panel substrate production, assembly and 3DHI is around 5800 panels per month, 4.20 million units per month, and 1100 units per months respectively.
8. **SiCSem Private Limited** is establishing semiconductor manufacturing facility in Odisha with an investment of Rs. 2,066 crores. The facility will be set up in technology partnership with Clas-SiC Wafer Fab Ltd. for SiC fab and Continental Device India Pvt. Ltd. for packaging. The production capacity is 5,000 wafers/month, and the packaging capacity is 8 million units/month.
9. **Continental Device India Private Limited (CDIL)** is expanding its semiconductor manufacturing facility in Punjab, with an investment of Rs. 117 crores. The facility will manufacture high-power discrete semiconductor devices such as MOSFETs, IGBTs, Schottky

Bypass Diodes, and transistors, both in Silicon and Silicon Carbide. The production capacity will be around 158.38 million units/annum.

10. **Advanced System in Package Technologies Private Limited (ASIP)** is establishing semiconductor manufacturing facility in Andhra Pradesh**,** with an investment of Rs. 480 crores. The facility will be set up in technology partnership with APACT Co. Ltd, South Korea. The production capacity of the facility would be around 96 million units/annum.

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